

通富微电子股份有限公司

可靠性试验报告

TONGFU MICROELECTRONICS LTD.CO.,

RELIABILITY TEST REPORT

题目: 265客户TSSOP20-NT-CU产品考核可靠性试验报告

(Subject) 265 customer TSSOP20-NT-CU product reliability report

目的: 对N32G030F6S7 (TSSOP20-NT-CU) 产品进行可靠性试验考核

(Purpose) Evaluate the reliability of N32G030F6S7 (TSSOP20-NT-CU)

产品信息:

(LOT BACKGROUND INFORMATION)

客户(Customer): 265

圆片型号(Wafer Type): N/A

品名(Sample Name): N32G030F6S7

封装形式(Package): TSSOP20-NT-CU

组装批号(Assembly Lot): 0YH05320101

装片胶(Epoxy): S210

框架(Leadframe): TSSOP20B

芯片尺寸(Die Size): N/A

键合丝(Wire): 0.8mil; EX1P

塑封料(Molding Compound): EME-G600F-TF

电镀成分(Plating Component): Pure Sn

试验结果:

(Result)

PASS

日期: April 20, 2021

(Date)

作成(Write By):

石微微

审核(Review By):

吴卫华

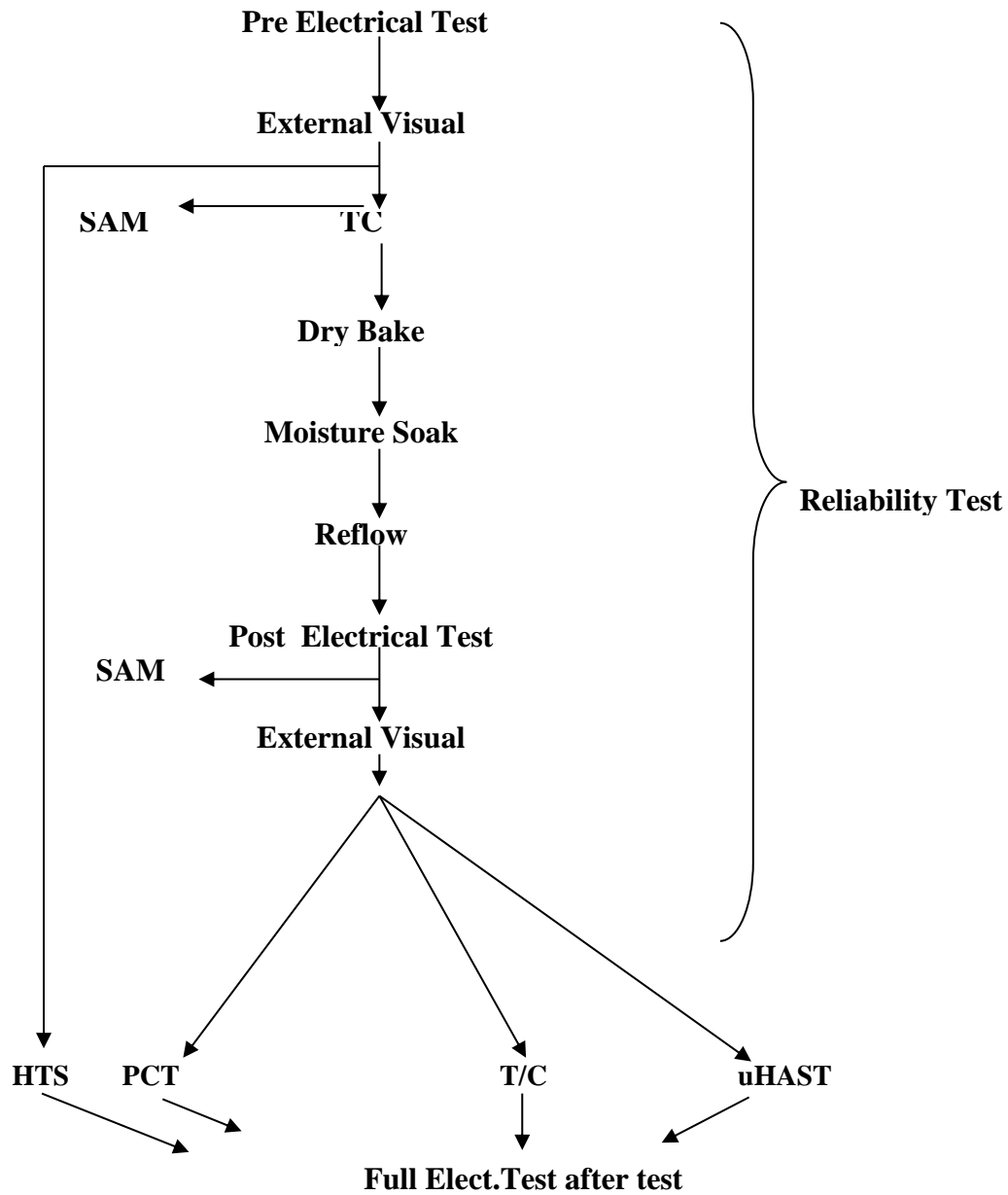
报告编号: RQ2021012505

(Report No.)

批准(Authorize):

平来

Test Flow



Solderability:

Preconditioning: Steam Aging 245°C Sn:Ag:Cu

试验结果:

(Summary Results)

(Summary of Results)		(Summary of Results)		
No.	Test Item	Result	Page	
1	Time Zero Elec.test	0/330	4,5,6,7,8,9,10	
2	External Visual	0/330		
3	Precondition L3	Time Zero SAM (50 MHz)	OK	4,5,6,9,10
4		T/C(-65℃(+0/-10)～+150℃(+10/-0)0.5h/c 5c)	Include PCT&T/C&uHAST	
5		Dry Bake (125(-0/+5)℃/24hrs)		
6		Moisture Soak (30±2℃/60±3％RH/192hrs)		
7		Reflow (260℃(min)/3cls)		
8		POST Precon.Elec. Test	0/231	
9		Post precon. SAM (50 MHz)	OK	
10		External Visual	0/231	
11	PCT (121±2℃/2atm/168hrs(-0/+5h)	0/77	4	
12	T/C (-65℃(+0/-10)～+150℃(+10/-0) 0.5h/c 500/1000cls)	0/77	5	
13	uHAST (130±2℃/85±5％RH/96hrs)	0/77	6	
14	HTS (150(-0/+10)℃/500/1000hrs)	0/77	7	
15	Solderability	0/22	8,9	

可靠性试验和结果

(Reliability Test and Result)

1 预处理 (PCT)

条件(Conditions):

温度循环(T/C)	-65℃ (+0/-10) ~ +150℃ (+10/-0) 0.5h/c5c
前烘(Dry Bake)	125 (-0/+5) °C/24hrs
吸湿(Moisture Soak)	30±2°C/60±3%RH/192hrs
回流(Reflow)	260°C (min)/3cls

电测试(Electrical Test):

预处理前后(Pre and Post Rreconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

外观检查(Visual Readouts):

预处理前后(Pre and Post Preconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

2 预处理后高压蒸煮试验(Preconditioning Autoclave Test)

条件(Conditions):

121±2°C/2atm/168hrs (-0/+5h)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

外观检查(Visual Readouts):

试验后(After Test)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

可靠性试验和结果

(Reliability Test and Result)

1 预处理(T/C)

条件(Conditions):

温度循环(T/C)	-65℃ (+0/-10) ~ +150℃ (+10/-0) 0.5h/c5c
前烘(Dry Bake)	125 (-0/+5) °C/24hrs
吸湿(Moisture Soak)	30±2°C/60±3%RH/192hrs
回流(Reflow)	260°C (min)/3cls

电测试(Electrical Test):

预处理前后(Pre and Post Rreconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

外观检查(Visual Readouts):

预处理前后(Pre and Post Preconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

2 预处理后温度循环试验(Preconditioning Temperature Cycle Test)

条件(Conditions):

-65℃ (+0/-10) ~ +150℃ (+10/-0) 0.5h/c 500/1000cls

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

外观检查(Visual Readouts):

试验后(After Test)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

可靠性试验和结果

(Reliability Test and Result)

1 预处理(uHAST)

条件(Conditions):

温度循环(T/C)	-65℃ (+0/-10) ~ +150℃ (+10/-0) 0.5h/c5c
前烘(Dry Bake)	125 (-0/+5) °C/24hrs
吸湿(Moisture Soak)	30±2°C/60±3%RH/192hrs
回流(Reflow)	260°C (min)/3cls

电测试(Electrical Test):

预处理前后(Pre and Post Reconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

外观检查(Visual Readouts):

预处理前后(Pre and Post Preconditioning)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

预处理前(Pre Pre.): 0/77

预处理后(Post Pre.): 0/77

2 预处理后uHAST试验(Preconditioning uHAST Test)

条件(Conditions):

130±2°C/85±5%RH/96hrs

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

外观检查(Visual Readouts):

试验后(After Test)

样品数(Sample Size):

77units

Ac/Re(Accept No.):

0/1

结果(Results):

试验后(After Test): 0/77

可靠性试验和结果

(Reliability Test and Result)

1 高温储存试验(High Temperature Storage Test)

条件(Conditions):	150 (-0/+10) °C/500/1000hrs		
样品数(Sample Size):	77units		
Ac/Re(Accept No.):	0/1		
结果(Results):	试验后(After Test):	0/77	
外观检查(Visual Readouts):	试验后(After Test)		
样品数(Sample Size):	77units		
Ac/Re(Accept No.):	0/1		
结果(Results):	试验后(After Test):	0/77	

可靠性试验和结果

(Reliability Test and Result)

1 预处理(Solderability)

条件(Conditions): ①蒸汽老化(Steam ageing) 93 (+3/-5) °C/8hrs±15min

外观检查(Visual Readouts): 预处理前后(Pre and Post Preconditioning)

样品数(Sample Size): 22units

Ac/Re(Accept No.): 0/1

结果(Results): 预处理前(Pre Pre.): 0/22

预处理后(Post Pre.): 0/22

2 预处理后易焊性试验(Preconditioning Solderability Test)

条件(Conditions): Sn:Ag:Cu=96.5:3.0:0.5/245±5°C/5±0.5s

外观检查(Visual Readouts): 试验后(After Test)

样品数(Sample Size): 22units

Ac/Re(Accept No.): 0/1

结果(Results): 试验后(After Test): 0/22

备注(Remark):

焊料类型(Solder): 锡银铜(SnAgCu) J-STD-006

助焊剂(Flux): MS-002D02

清洗液(Lotion): 无水乙醇(Absolute Alcohol)

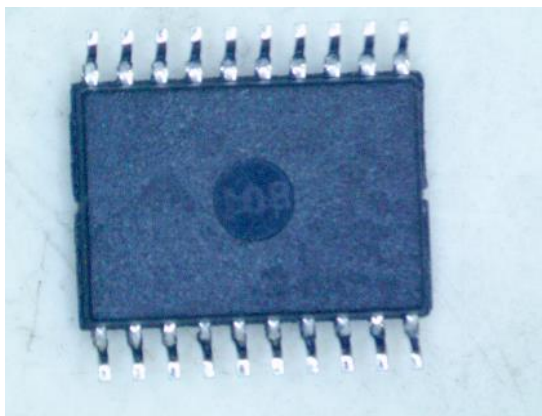
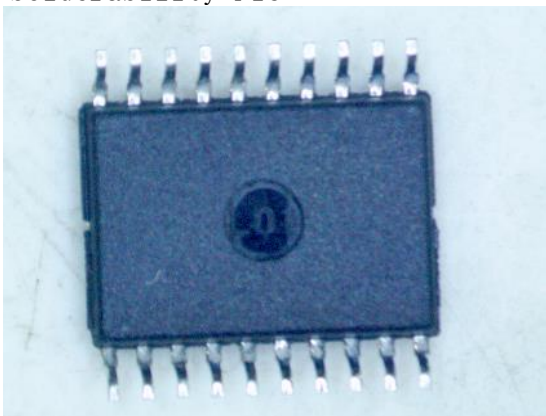
速度(Speed): 25±6mm/s

检查倍数(Magnification): 10X-30X

Reflow Profile

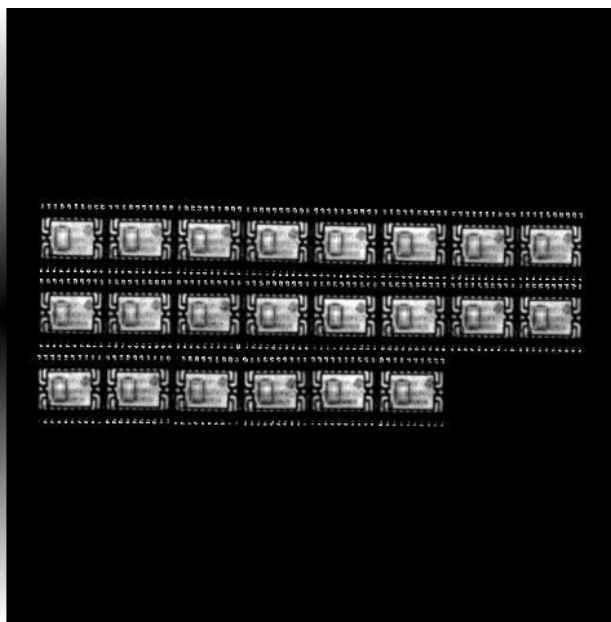


Solderability Pic



超声波扫描图(Pics of SAM)

before Pre



after Pre

